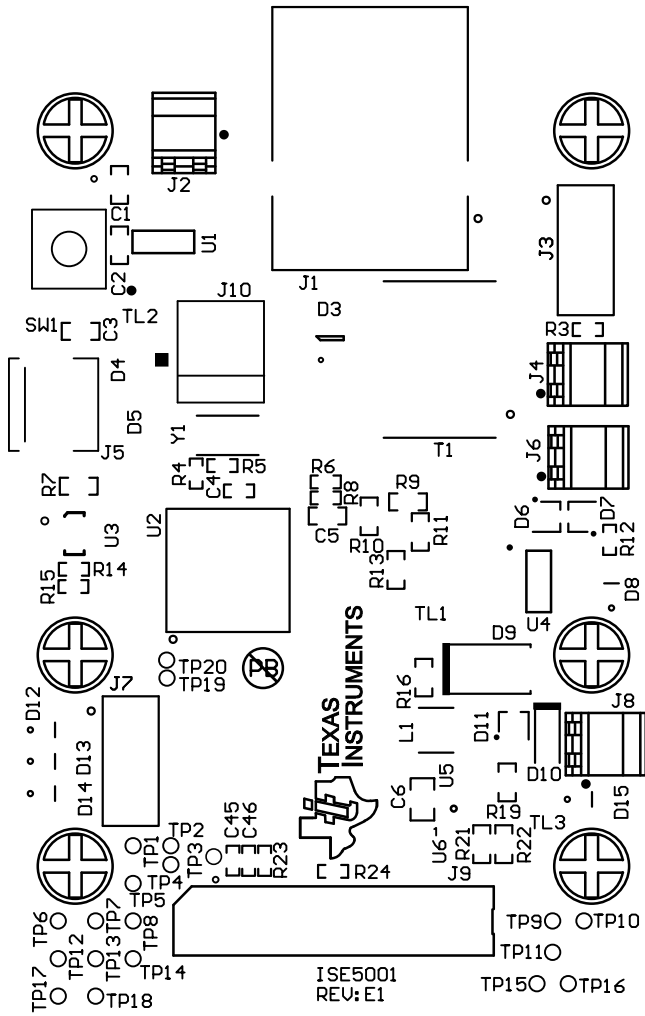
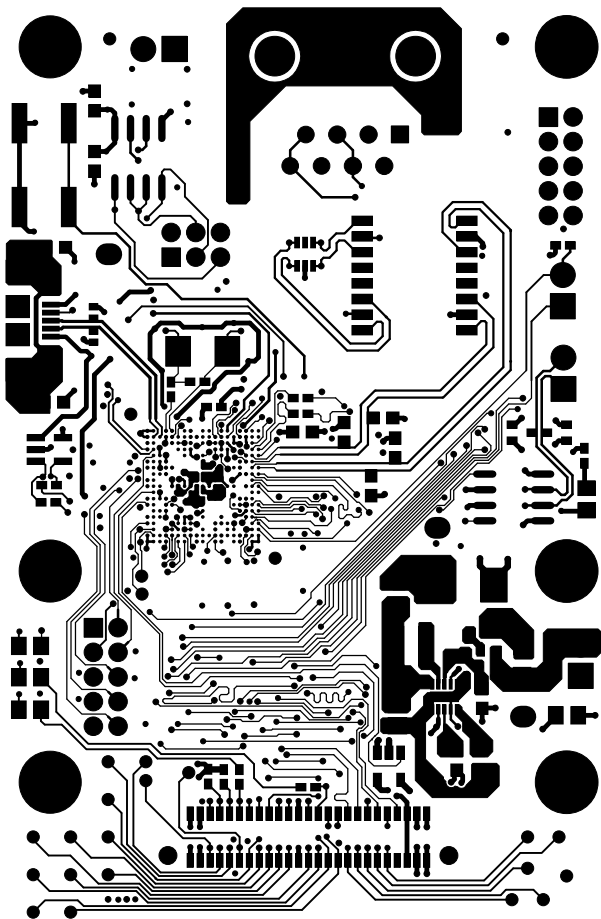


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Soldermask Top	TIDA-00226 (ISE5001)		
PLOT NAME = ISE5001.GTS	GENERATED:	6/25/2014 6:48:54 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TIDA-00226 <ISE5001>		
PLOT NAME = ISE5001.GTO	GENERATED:	6/25/2014 6:48:53 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #:

REV: E1

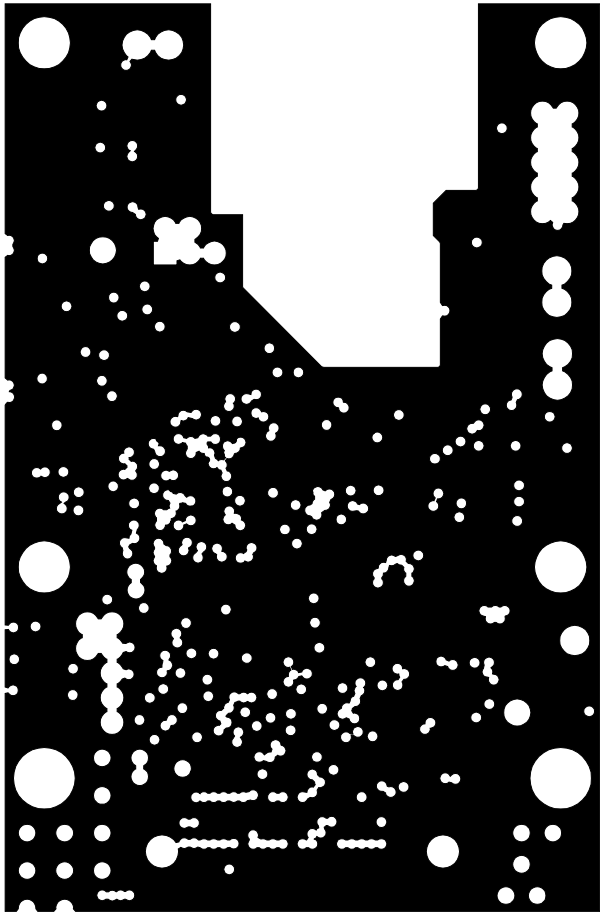
SUN REV: Not In VersionControl

LAYER NAME = TOP LAYER

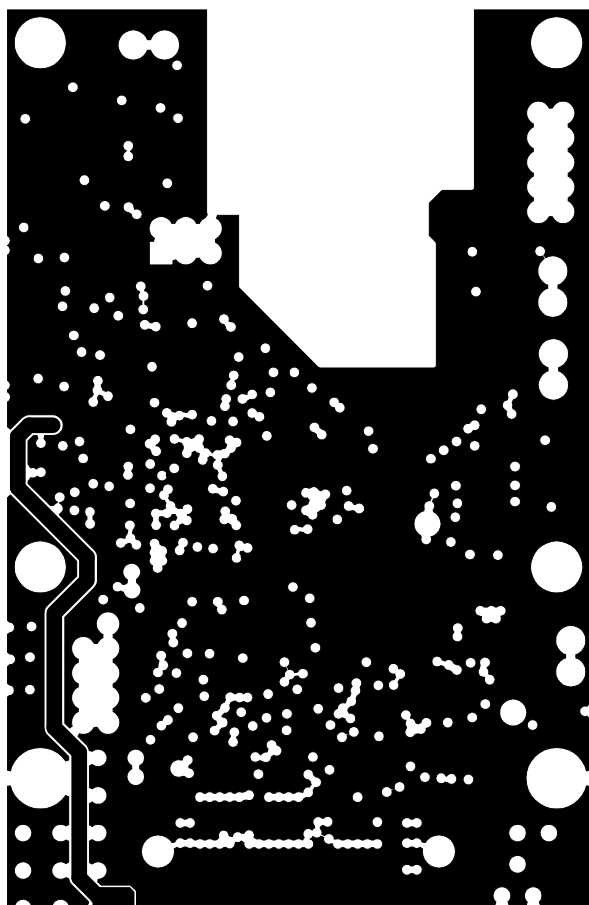
TIDA-00226 (ISE5001)

PLOT NAME = ISE5001.GTL

GENERATED: 6/25/2014 6:48:53 PM TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = L2_GND-PLANE	TIDA-00226 (ISE5001)		
PLOT NAME = ISE5001.G1	GENERATED:	6/25/2014 6:36:57 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #:

REV: E1

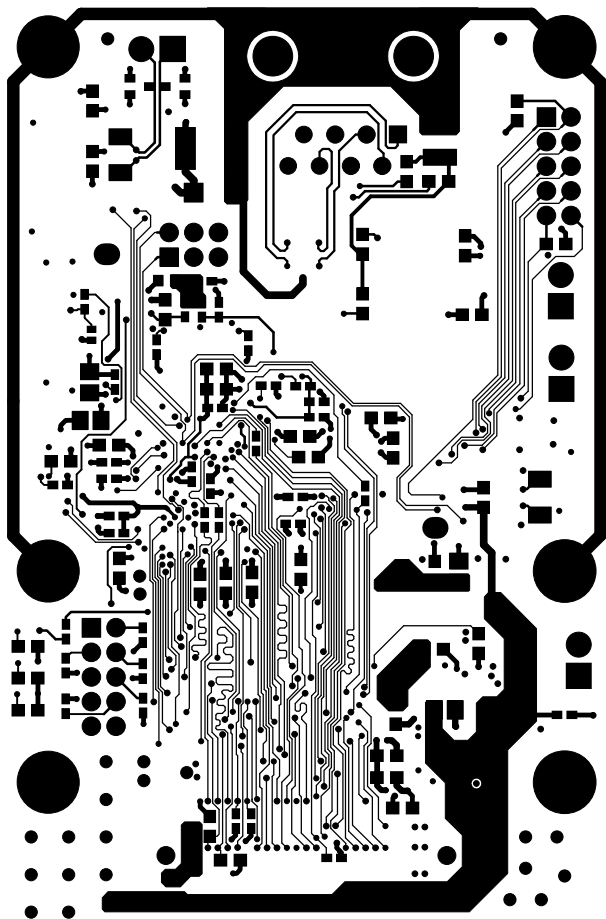
SUN REV: Not In VersionControl

LAYER NAME = L3_PWR-PLANE

TIDA-00226 (ISE5001)

PLOT NAME = ISE5001.G2

GENERATED: 6/25/2014 6:36:57 PM TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #:

REV: E1

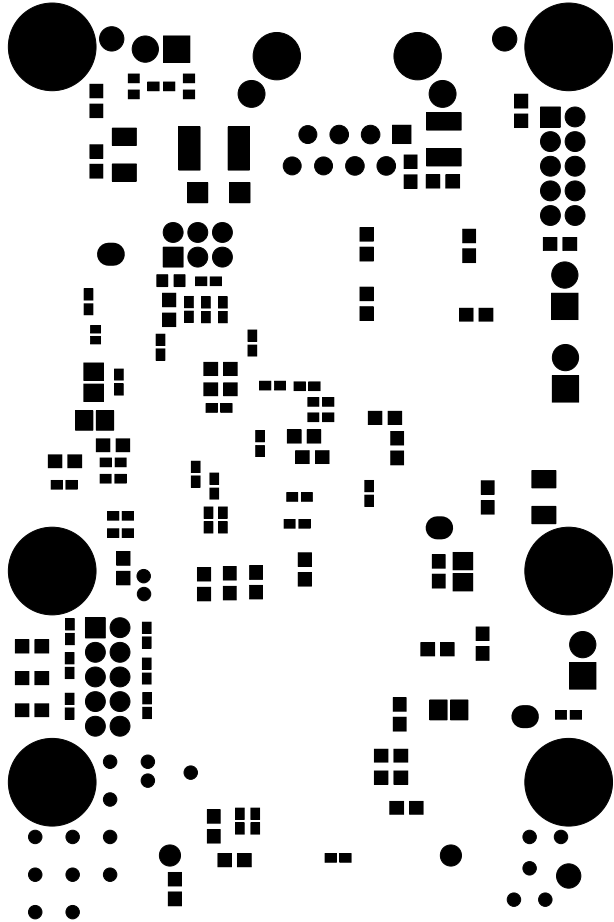
SUN REV: Not In VersionControl

LAYER NAME = BOTTOM LAYER

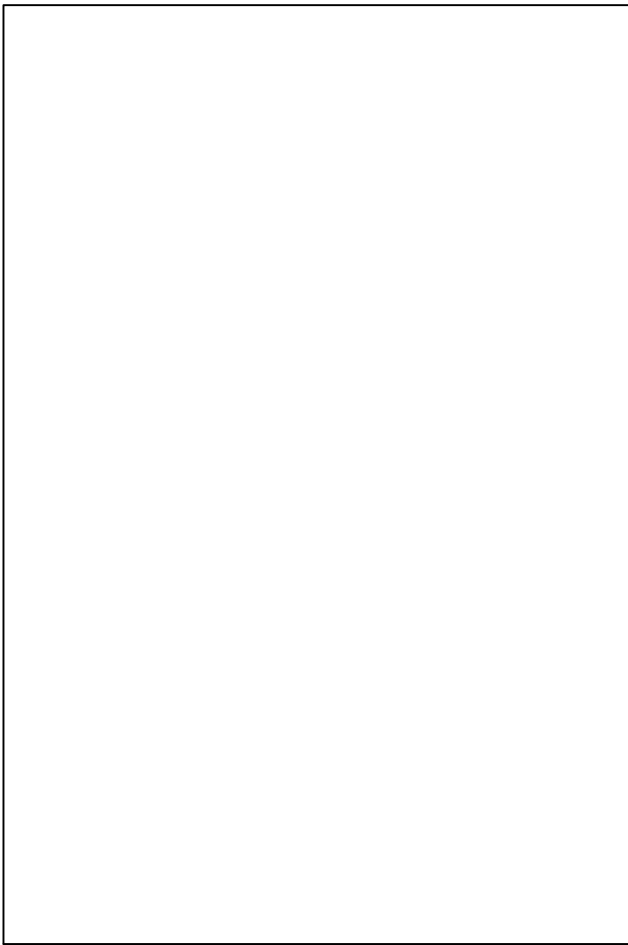
TIDA-00226 (ISE5001)

PLOT NAME = ISE5001.GBL

GENERATED: 6/25/2014 6:48:53 PM TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Soldermask Bottom	TIDA-00226 (ISE5001)		
PLOT NAME = ISE5001.GBS	GENERATED:	6/25/2014 6:48:54 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TIDA-00226 (ISE5001)		
PLOT NAME = ISE5001.GM1	GENERATED:	6/25/2014 6:48:54 PM	TEXAS INSTRUMENTS

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